

FORM PTO-1449				Atty. Docket Number: H60-104 US				Serial Number: 10/002,996						
LIST OF PRIOR ART CITED BY APPLICANT				Applicant: J. Ramm										
				Filing Date: 10/25/01				Group: 1765						
U.S. PATENT DOCUMENTS														
<div style="position: absolute; top: 0; left: 0; width: 100%; height: 100%; border: 1px solid black; border-radius: 50%; text-align: center; line-height: 100%;"> MAR 12 2002 U.S. PATENT & TRADEMARK OFFICE </div>	<div style="position: absolute; top: 0; left: 0; width: 100%; height: 100%; border: 1px solid black; border-radius: 50%; text-align: center; line-height: 100%;"> MAR 12 2002 U.S. PATENT & TRADEMARK OFFICE </div>	Document Number		Date		Name		Class		Sub-class		Filing Date		
FA	AA	4	0	5	8	4	3	0	11/15/77	Suntola et al.		156	611	11/25/75
↑	AB	4	3	8	9	9	7	3	06/28/83	Suntola et al.		118	275	12/11/81
	AC	4	4	1	3	0	2	2	11/01/83	Suntola et al.		427	255.2	06/21/79
	AD	5	0	7	1	6	7	0	12/10/91	Kelly		427	38	06/11/90
	AE	5	9	1	6	3	6	5	06/29/99	Sherman		117	92	08/16/96
↓	AF	5	9	7	2	4	3	0	10/26/99	DiMeo, Jr. et al.		427	255.3	11/26/97
EH	AG	6	0	1	5	5	9	0	01/18/00	Suntola et al.		427	255.2	11/28/95
	AH													
	AI													
	AJ													
	AK													
FOREIGN PATENT DOCUMENTS														
		Document Number		Date		Country		Class		Sub-class		Translated		
												Y	N	
	AL													
	AM													
	AN													
	AO													
	AP													
Other Prior Art (incl. Author, Title, Date, Pertinent Pages, etc.)														
FA	AR	Hiramatsu, K, et al., "Formation of TiN films with low CI concentration by pulsed plasma chemical vapor deposition", <u>J. Vac. Sci. Technol.</u> A 14(3) May/Jun 1996, 1037-1040.												
FA	AS	Rossnagel, S.M., "Plasma-enhanced atomic layer deposition of Ta and Ti for interconnect diffusion barriers", <u>J. Vac. Sci. Technol.</u> B 18(4), Jul/Aug 2000, 2016-2020.												
FA	AT	Swiss Search Report, dated July 27, 2001.												
Examiner: <i>J. D. [Signature]</i>				Date Considered: <i>7/20/02</i>										
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with M Draw line through citation if not in conformance and not considered. Include copy of this f next communication to applicant.														